
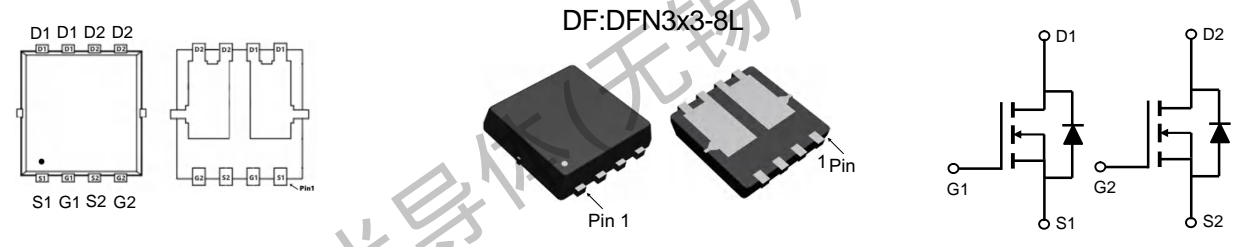


TMG25H06DF

N+N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low R_{DS(ON)} • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>V_{DS} = 60V I_D = 25A</p> <p>R_{DS(ON)} = 11 mΩ (Typ.) @ V_{GS} = 10V</p> <p>100% UIS Tested 100% R_g Tested</p> 
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DF:DFN3x3-8L

Marking:25V06

Absolute Maximum Ratings (T_C = 25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V	25	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V	18	A
I _{DM}	Pulsed Drain Current	136	A
EAS	Single Pulse Avalanche Energy	33.8	mJ
I _{AS}	Avalanche Current	---	A
P _D @T _C =25°C	Total Power Dissipation	27	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient	---	55	°C/W
R _{θJC}	Thermal Resistance Junction-Case	---	4.6	°C/W

TMG25H06DF

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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V_{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60	-	-	V	
Gate-Body Leakage Current	I_{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	V _{DS} = 65V, V _{GS} = 0V	T _J =25°C	-	-	1	μA
			T _J =100°C	-	-	100	
Gate-Threshold Voltage	V_{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	2.0	3.0	V	
Drain-Source on-Resistance	R_{DS(on)}	V _{GS} = 10V, I _D = 20A	-	11	15	mΩ	
		V _{GS} = 4.5V, I _D = 10A	-	14	21		
Forward Transconductance	g_{fs}	V _{DS} = 10V, I _D = 20A	-	42	-	S	
Dynamic Characteristics							
Input Capacitance	C_{iss}	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz	-	738	-	pF	
Output Capacitance	C_{oss}		-	225	-		
Reverse Transfer Capacitance	C_{rss}		-	13.5	-		
Gate Resistance	R_G	f = 1MHz	-	1.2	-	Ω	
Switching Characteristics							
Total Gate Charge	Q_g	V _{GS} = 10V, V _{DS} = 30V, I _D = 20A	-	14	-	nC	
Gate-Source Charge	Q_{gs}		-	2.6	-		
Gate-Drain Charge	Q_{gd}		-	2.9	-		
Turn-on Delay Time	t_{d(on)}	V _{GS} = 10V, V _{DD} = 30V, R _G = 3Ω, I _D = 20A	-	5.7	-	ns	
Rise Time	t_r		-	5.1	-		
Turn-off Delay Time	t_{d(off)}		-	14.8	-		
Fall Time	t_f		-	4.6	-		
Body Diode Reverse Recovery Time	t_{rr}	I _F = 20A, dI/dt = 100A/μs	-	24	-	ns	
Body Diode Reverse Recovery Charge	Q_{rr}		-	9.6	-	nC	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage	V_{SD}	I _S = 20A, V _{GS} = 0V	-	-	1.2	V	
Continuous Source Current	T _C =25°C	I_S	-	-	25	A	

TMG25H06DF

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Typical Characteristics

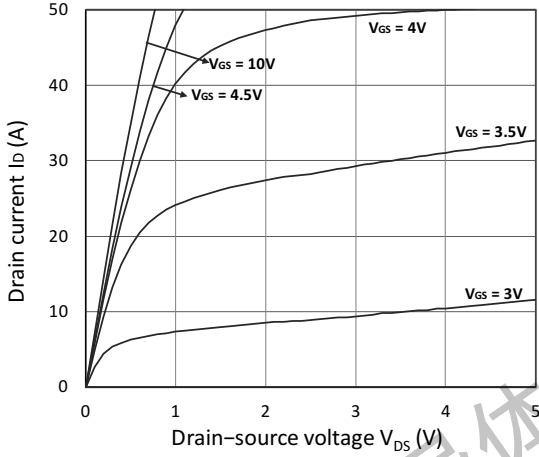


Figure 1. Output Characteristics

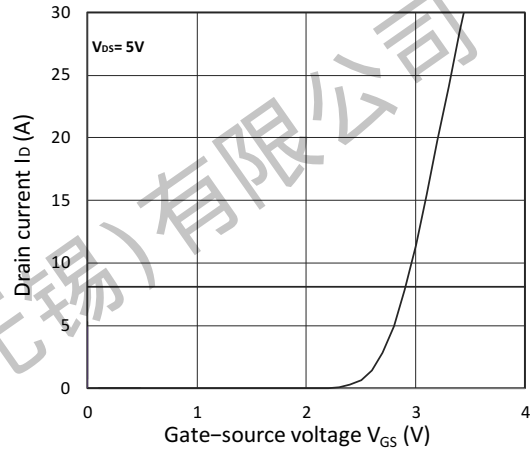


Figure 2. Transfer Characteristics

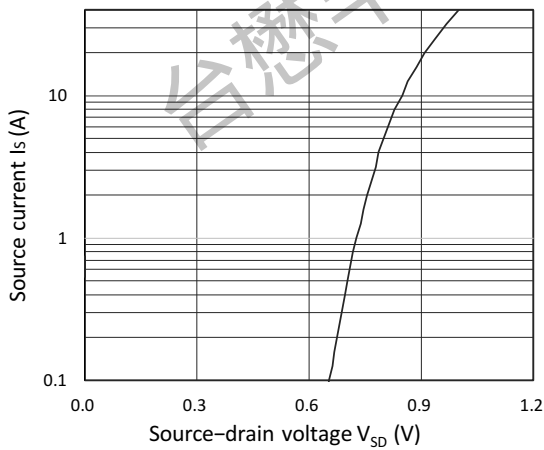


Figure 3. Forward Characteristics of Reverse

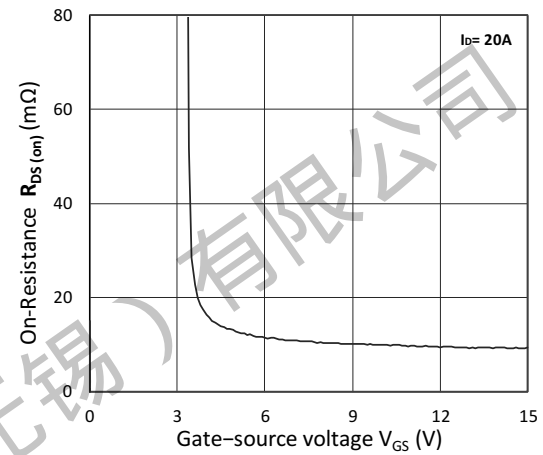


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

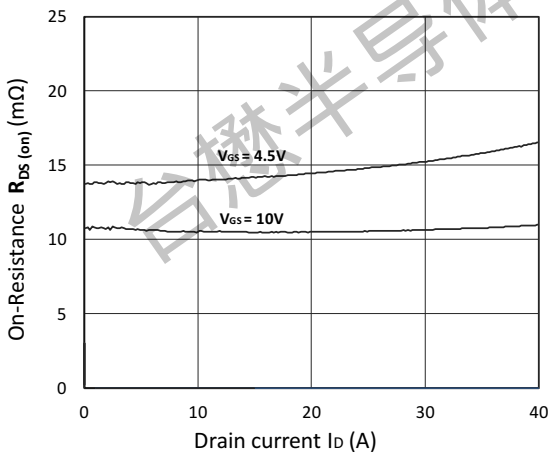


Figure 5. $R_{DS(ON)}$ vs. I_D

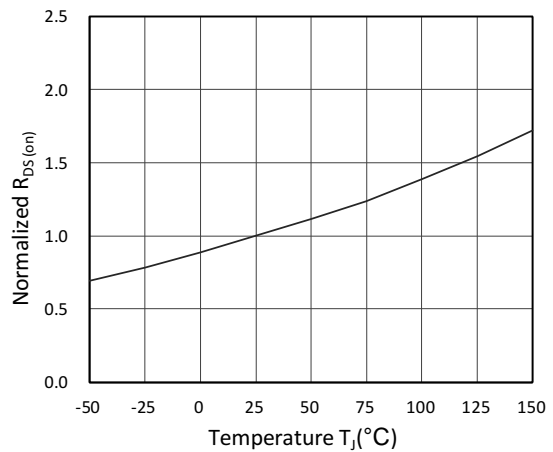


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

TMG25H06DF

N+N-Channel Enhancement Mosfet

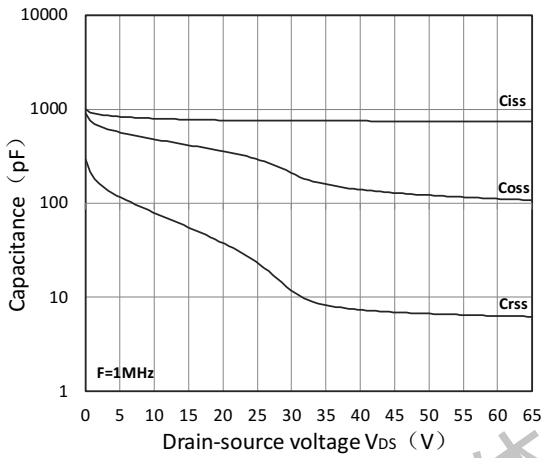


Figure 7. Capacitance Characteristics

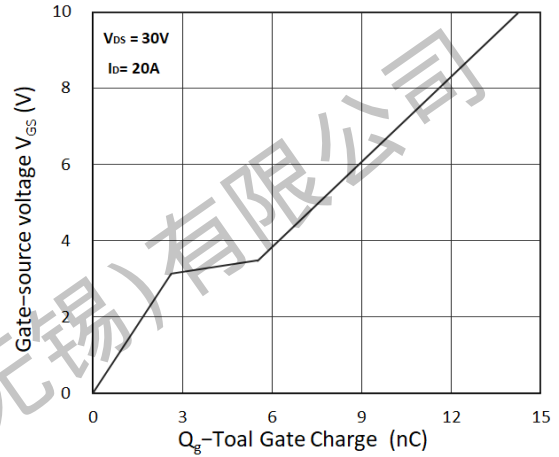


Figure 8. Gate Charge Characteristics

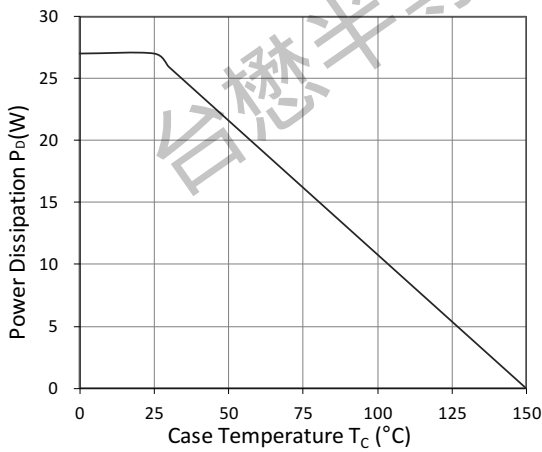


Figure 9. Power Dissipation

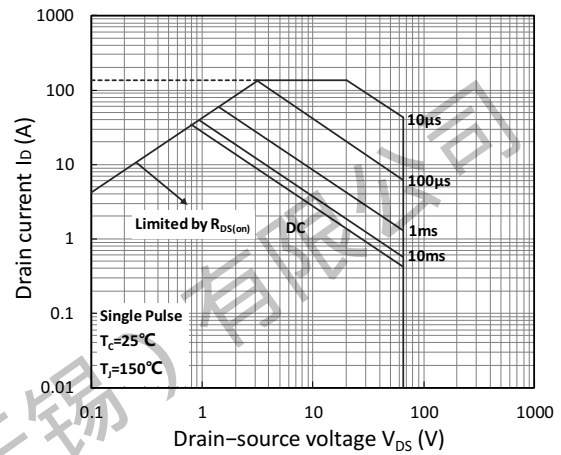


Figure 10. Safe Operating Area

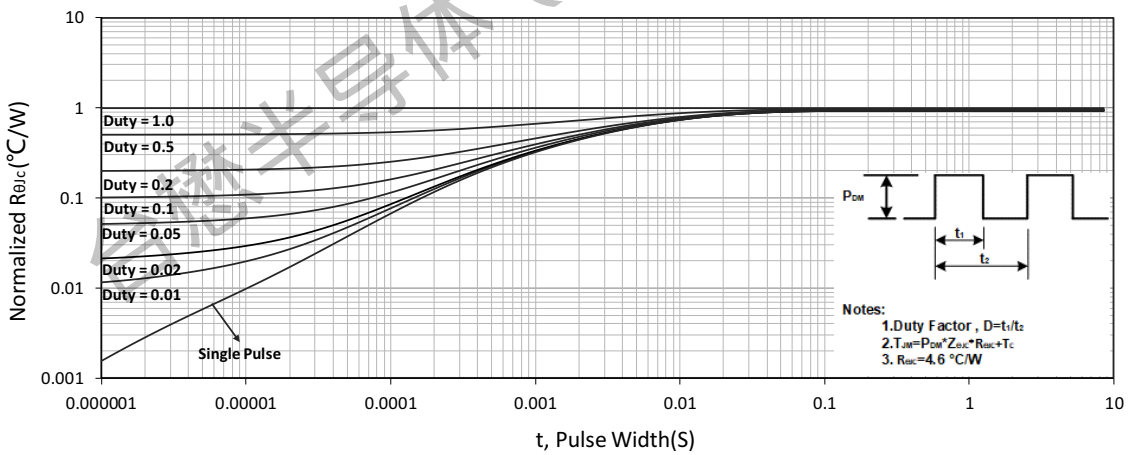
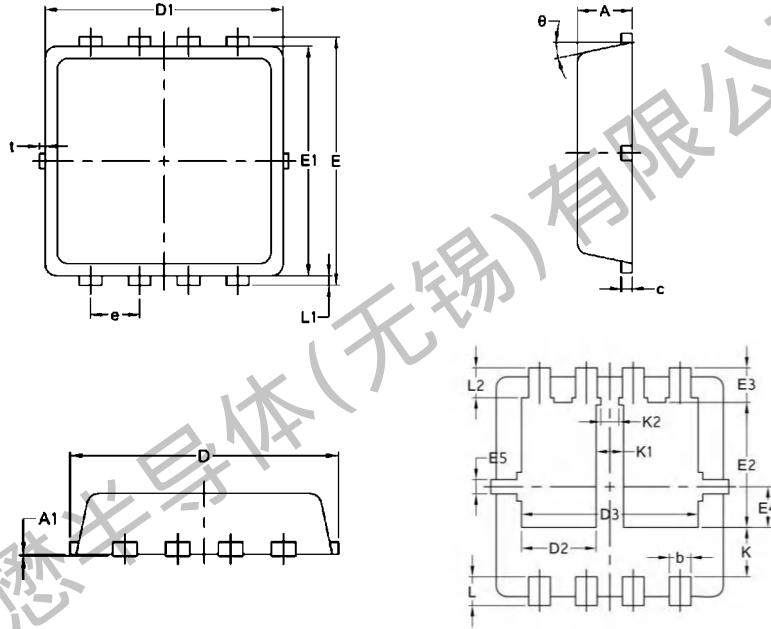


Figure 11. Normalized Maximum Transient Thermal Impedance

TMG25H06DF

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Package Mechanical Data:DFN3x3-8L

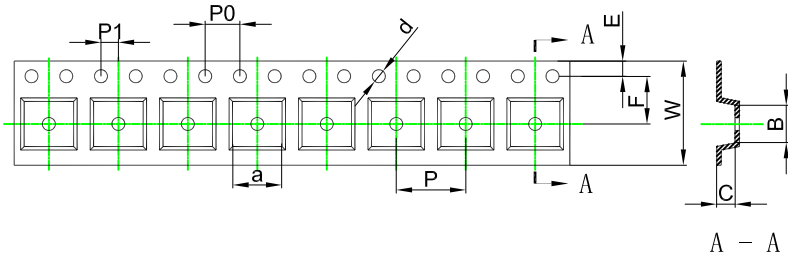


Symbol	Common		
	Min	Mm	Max
		Nom	
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.25	0.30	0.39
c	0.14	0.152	0.20
D	3.20	3.30	3.45
D1	3.05	3.15	3.25
D2	0.84	1.04	1.24
D3	2.30	2.45	2.60
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.60	1.74	1.90
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.50	0.69	0.80
K1	0.30	0.38	0.53
K2	0.15	0.25	0.35
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
L2	0.27	0.42	0.57
t	0	0.075	0.13
Φ	10°	12°	14°

TMG25H06DF

N+N-Channel Enhancement Mosfet

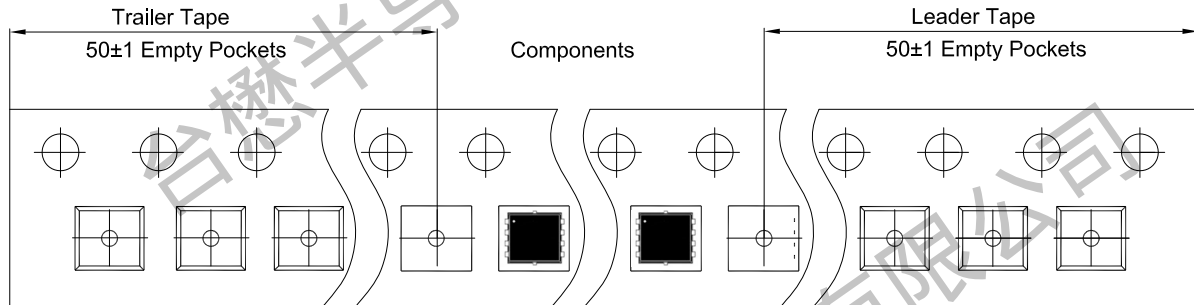
PDFN3x3-8L Embossed Carrier Tape



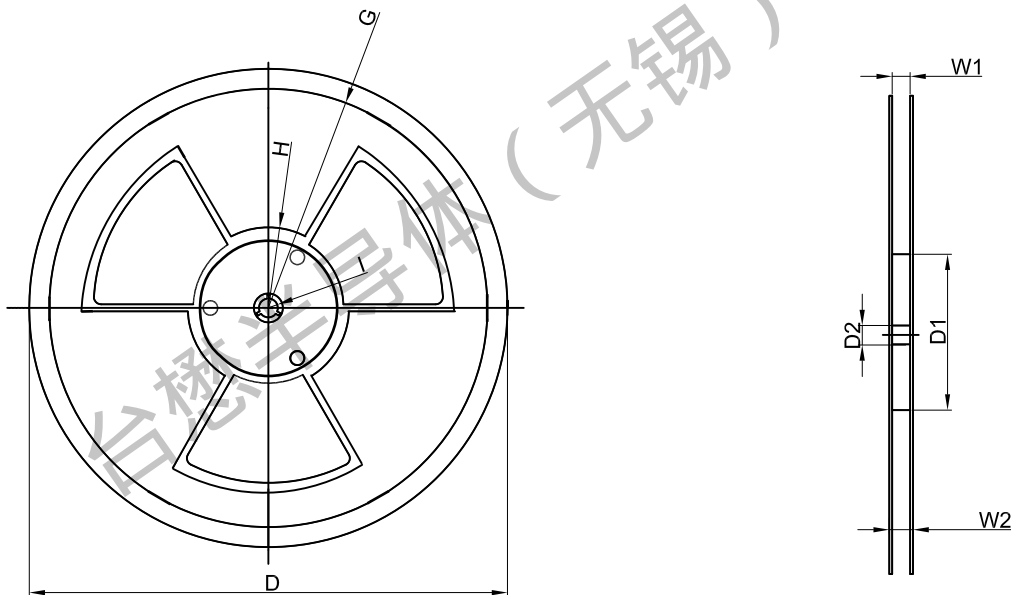
Packaging Description:
SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
PDFN3x3-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

PDFN3x3-8L Tape Leader and Trailer



PDFN3x3-8L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13"Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
5,000 pcs	13 inch	10,000 pcs	370×355×52	50,000 pcs	400×360×368	

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Revision history:

Date	Rev	Description	Page
2023.05.14	23.05	Original	